

ABSTRACT OF THE DISCLOSURE

In a semiconductor device having CSP structure, reinforcing pads are provided on corners of the mounting surface of the CSP body portion, and a plurality of solder balls are mounted on the reinforcing pads, respectively. Each of the reinforcing pads has a periphery adjacent to each of the solder balls mounted thereon that is at least semicircular, when seen in plan view. This structure avoids acute angle portions which mechanical stress is concentrated. As a result, peeling of solder balls from the reinforcing pad can be reduced.

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